

Fan-out Panel-level Packaging Market - Global Outlook and Forecast 2022-2028

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Abstracts

This report contains market size and forecasts of Fan-out Panel-level Packaging in Global, including the following market information:

Global Fan-out Panel-level Packaging Market Revenue, 2017-2022, 2023-2028, (\$ millions)

Global top five companies in 2021 (%)

The global Fan-out Panel-level Packaging market was valued at 1409.5 million in 2021 and is projected to reach US\$ 4721.9 million by 2028, at a CAGR of 18.9% during the forecast period.

The U.S. Market is Estimated at \$ Million in 2021, While China is Forecast to Reach \$ Million by 2028.

System-in-package (SiP) Segment to Reach \$ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of Fan-out Panel-level Packaging include Amkor Technology, Deca Technologies, Lam Research Corporation, Qualcomm Technologies, Siliconware Precision Industries, SPTS Technologies, STATS ChipPAC, Samsung and TSMC. etc. In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Fan-out Panel-level Packaging companies, and industry experts on this industry, involving the revenue,

demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Fan-out Panel-level Packaging Market, by Type, 2017-2022, 2023-2028 (\$ millions)

Global Fan-out Panel-level Packaging Market Segment Percentages, by Type, 2021 (%)

System-in-package (SiP)

Heterogeneous Integration

Global Fan-out Panel-level Packaging Market, by Application, 2017-2022, 2023-2028 (\$ millions)

Global Fan-out Panel-level Packaging Market Segment Percentages, by Application, 2021 (%)

Wireless Devices

Power Management Units

Radar Devices

Processing Units

Others

Global Fan-out Panel-level Packaging Market, By Region and Country, 2017-2022, 2023-2028 (\$ Millions)

Global Fan-out Panel-level Packaging Market Segment Percentages, By Region and Country, 2021 (%)

North America

US

Canada

Mexico

Europe

Germany

France

U.K.

Italy

Russia

Nordic Countries

Benelux

Rest of Europe

Asia

China

Japan

South Korea

Southeast Asia

India

Rest of Asia

South America

Brazil

Argentina

Rest of South America

Middle East & Africa

Turkey

Israel

Saudi Arabia

UAE

Rest of Middle East & Africa

Competitor Analysis

The report also provides analysis of leading market participants including:

Key companies Fan-out Panel-level Packaging revenues in global market, 2017-2022 (estimated), (\$ millions)

Key companies Fan-out Panel-level Packaging revenues share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:

Amkor Technology

Deca Technologies

Lam Research Corporation

Qualcomm Technologies

Siliconware Precision Industries

SPTS Technologies

STATS ChipPAC

Samsung

TSMC

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